

# Electronic Filing System (EFS) Data

## Electronic Patent Application Submission

### USPTO Use Only

EFS ID: 53688

Application ID: 10667227



Title of Invention:

SEMICONDUCTOR PACKAGE AND  
METHOD OF MAKING  
LEADFRAME HAVING LEAD  
LOCKS TO SECURE LEADS TO  
ENCAPSULANT

First Named Inventor: Jae Yee

Domestic/Foreign Application: Domestic Application

Filing Date: 2003-09-18

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Submission Type: Information Disclosure  
Statement

Filing Type:

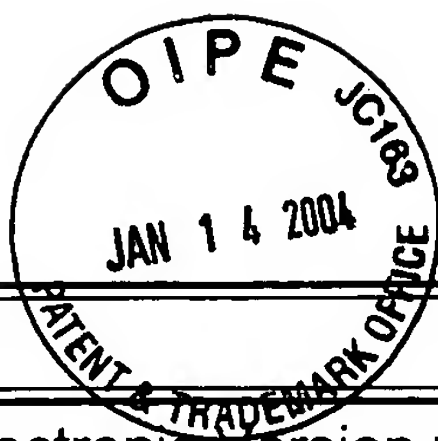
Confirmation number: 7012

Attorney Docket Number: AMKOR012G1

Total Fees Authorized:

Digital Certificate Holder: cn=Mark B. Garred,ou=Registered Attorneys,ou=Patent and Trademark  
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Certificate Message Digest: 0f86bcea1c9109d6cdac92e6c19821ba894b963f

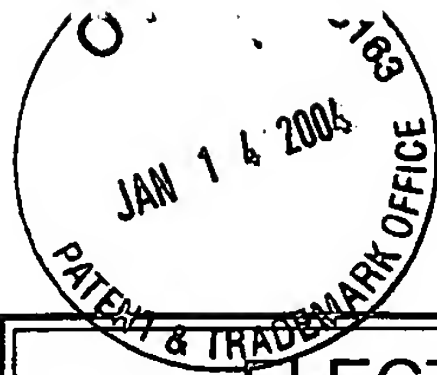


# TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	SEMICONDUCTOR PACKAGE AND METHOD OF MAKING LEADFRAME HAVING LEAD LOCKS TO SECURE LEADS TO ENCAPSULANT									
Application Number: 10/667227 										
Date: 2003-09-18										
First Named Applicant: Jae Hak Yee										
Confirmation Number: 7012										
Attorney Docket Number: AMKOR012G1										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mark B. Garred Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mark B. Garred Registered Number: 34,823	/mbg/	Attorney		
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<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids2-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids2-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files									
us-ids	ids2-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
Comments										



## ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

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<div>Application Number: 10/667227</div> <div>Confirmation Number: 7012</div> <div>First Named Applicant: Jae Yee</div> <div>Attorney Docket Number: AMKOR012G1</div> <div>Art Unit: 2812</div> <div>Search string: ( 5221642 or 5250841 or 5252853 or 5258094 or 5266834 or 5273938 or 5278446 or 5277972 or 5279029 or 5281849 or 5294897 or 5327008 or 5332864 or 5336931 or 5335771 or 5343076 or 5358905 or 5365106 or 5381042 or 5391439 or 5406124 or 5410180 or 5414299 or 5424576 or 5428248 or 5435057 or 5444301 or 5452511 or 5454905 or 5474958 or 5484274 or 5493151 or 5508556 or 5517056 or 5521429 or 5528076 or 5534467 or 5539251 or 5543657 or 5545923 or 5544412 or 5581122 or 5592025 or 5592019 or 5594274 or 5595934 or 5604376 or 5608267 or 5625222 or 5633528 ).pn.</div> <div>US Patent Documents</div> <div>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</div> <table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td></td><td>1</td><td>5221642</td><td>1993-06-22</td><td>BURNS</td><td></td><td></td><td></td></tr><tr><td></td><td>2</td><td>5250841</td><td>1993-10-05</td><td>SLOAN ET AL.</td><td></td><td></td><td></td></tr><tr><td></td><td>3</td><td>5252853</td><td>1993-10-12</td><td>MICHII</td><td></td><td></td><td></td></tr><tr><td></td><td>4</td><td>5258094</td><td>1993-11-02</td><td>FURUI ET AL.</td><td></td><td></td><td></td></tr><tr><td></td><td>5</td><td>5266834</td><td>1993-11-30</td><td>NISHI ET AL.</td><td></td><td></td><td></td></tr><tr><td></td><td>6</td><td>5273938</td><td>1993-12-28</td><td>LIN ET AL.</td><td></td><td></td><td></td></tr><tr><td></td><td>7</td><td>5278446</td><td>1994-01-11</td><td>NAGARAJ ET AL.</td><td></td><td></td><td></td></tr><tr><td></td><td>8</td><td>5277972</td><td>1994-01-11</td><td>SAKUMOTO ET AL.</td><td></td><td></td><td></td></tr><tr><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td></tr></tbody></table>							init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass		1	5221642	1993-06-22	BURNS					2	5250841	1993-10-05	SLOAN ET AL.					3	5252853	1993-10-12	MICHII					4	5258094	1993-11-02	FURUI ET AL.					5	5266834	1993-11-30	NISHI ET AL.					6	5273938	1993-12-28	LIN ET AL.					7	5278446	1994-01-11	NAGARAJ ET AL.					8	5277972	1994-01-11	SAKUMOTO ET AL.											
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	13	5332864	1994-07-26	LIANG ET AL.
	14	5336931	1994-08-09	JUSKEY ET AL.
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	16	5343076	1994-08-30	KATAYAMA ET AL.
	17	5358905	1994-10-25	CHIU
	18	5365106	1994-11-15	WATANABE
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	20	5391439	1995-02-21	TOMITA ET AL.
	21	5406124	1995-04-11	MORITA ET AL.
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	23	5414299	1995-05-09	WANG ET AL.
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	26	5435057	1995-07-25	BINDRA ET AL.
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	33	5508556	1996-04-16	LIN
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	39	5543657	1996-08-06	DIFFENDERFER ET AL.
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	42	5581122	1996-12-03	CHAO ET AL.
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	44	5592019	1997-01-07	UEDA ET AL.

	45	5594274	1997-01-14	SUETAKI
	46	5595934	1997-01-21	KIM
	47	5604376	1997-02-18	HAMBURGEN ET AL.
	48	5608267	1997-03-04	MAHULIKAR ET AL.
	49	5625222	1997-04-29	YONEDA ET AL.
	50	5633528	1997-05-27	ABBOTT ET AL.

Signature

Examiner Name	Date